



SOT1026-1

plastic thermal enhanced very very thin quad flat package;
no leads; 28 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.75 mm
body

13 August 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HWQFN28
Package type industry code	HWQFN28
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-08-2007
Manufacturer package code	SOT1026-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	-	-	0.8	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	28	-	



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2 Package outline

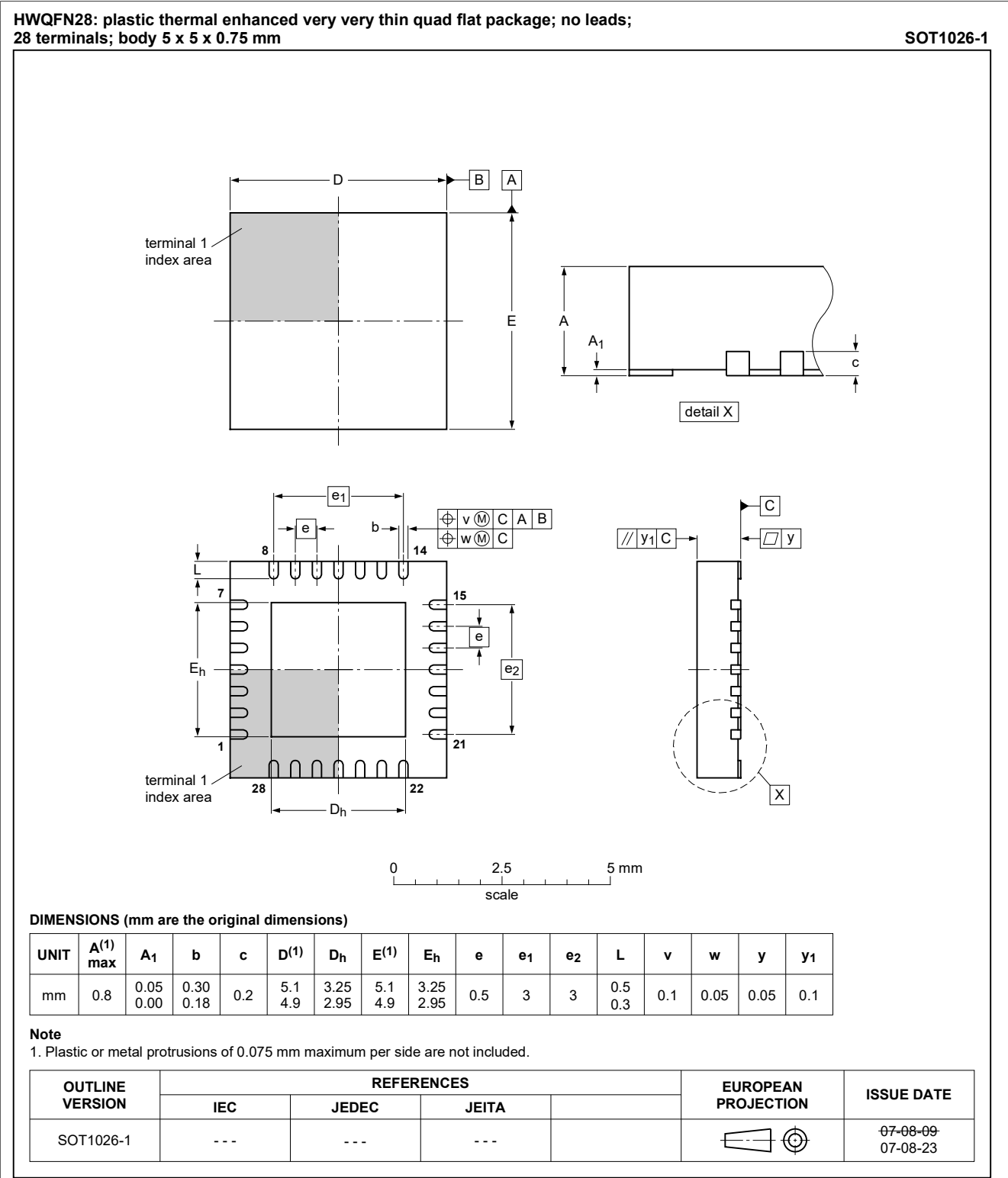


Figure 1. Package outline HWQFN28 (SOT1026-1)

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3 Legal information

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